

The China SMT Forum is an integrated information platform with a conference and an exhibition. The conference provides high-class expertise in technologies and applications for utilization in SMT-related enterprises. The exhibition gives an overview of today's marketplace.

The conference will welcome speakers and delegates from the electronic packaging, assembly, and system integration industry to the most progressive trading platform in China.

Call for Papers

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SUBMISSION

Please send an abstract of your paper to the program committee, including your title, name, position, and biography to:

papers@chinasmtforum.com

BEST PAPER AWARDS

During the China SMT Forum, two awards will be conferred in the following categories:

- » Committee Award
- » Audience Award

IMPORTANT DATES

- » Deadline for submission..... **April 30, 2008**
- » Notification of paper acceptance..... **June 1, 2008**
- » Delivery of manuscripts..... **August 31, 2008**
- » Delivery of presentations..... **September 30, 2008**
- » Registration deadline..... **October 31, 2008**

TOPICS

You are kindly invited to submit abstracts of proposed papers to China's Premier SMT, packaging, and assembly event. Topics of interest include but are not limited to:

- » Lead-free Soldering and RoHS-conform Technologies
- » Semiconductor Packaging and Power Electronics
- » PCB Technologies, Surface Finishes and Quality
- » Reliability and Testing
- » Assembling and Soldering Technologies
- » Electronic Markets and Future Trends

SUBMISSION GUIDELINES

- » Papers and abstracts (approx. 300 words) must be delivered in English. Abstracts are due **April 30, 2008**.
- » Papers should be 6-12 pages long (including illustrations).
- » The presentation will be limited to 30 minutes, including questions and answers.
- » Speaker and publication guidelines will be provided upon acceptance and will be available online by **June 1, 2008**.



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PROCEEDINGS

All accepted presentations will be published in the proceedings. Papers not complying with the publication guidelines may be rejected.

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